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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

# **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1664
Number of Logic Elements/Cells	16640
Total RAM Bits	212992
Number of I/O	488
Number of Gates	1052000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k400efi672-2x

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations
- Altera MegaCore® functions and Altera Megafunction Partners Program (AMPP<sup>SM</sup>) megafunctions
- NativeLink<sup>TM</sup> integration with popular synthesis, simulation, and timing analysis tools
- Quartus II SignalTap<sup>®</sup> embedded logic analyzer simplifies in-system design evaluation by giving access to internal nodes during device operation
- Supports popular revision-control software packages including PVCS, Revision Control System (RCS), and Source Code Control System (SCCS)

Device	144-Pin TQFP	208-Pin PQFP RQFP	240-Pin PQFP RQFP	356-Pin BGA	652-Pin BGA	655-Pin PGA
EP20K30E	92	125				
EP20K60E	92	148	151	196		
EP20K100	101	159	189	252		
EP20K100E	92	151	183	246		
EP20K160E	88	143	175	271		
EP20K200		144	174	277		
EP20K200E		136	168	271	376	
EP20K300E			152		408	
EP20K400					502	502
EP20K400E					488	
EP20K600E					488	
EP20K1000E					488	
EP20K1500E					488	

Table 5. APEX 20K FineLine BGA Package Options & I/O Count Notes (1), (2)									
Device	144 Pin	324 Pin	484 Pin	672 Pin	1,020 Pin				
EP20K30E	93	128							
EP20K60E	93	196							
EP20K100		252							
EP20K100E	93	246							
EP20K160E			316						
EP20K200			382						
EP20K200E			376	376					
EP20K300E				408					
EP20K400				502 <i>(3)</i>					
EP20K400E				488 (3)					
EP20K600E				508 (3)	588				
EP20K1000E				508 (3)	708				
EP20K1500E					808				

#### Notes to Tables 4 and 5:

- (1) I/O counts include dedicated input and clock pins.
- (2) APEX 20K device package types include thin quad flat pack (TQFP), plastic quad flat pack (PQFP), power quad flat pack (RQFP), 1.27-mm pitch ball-grid array (BGA), 1.00-mm pitch FineLine BGA, and pin-grid array (PGA) packages.
- (3) This device uses a thermally enhanced package, which is taller than the regular package. Consult the *Altera Device Package Information Data Sheet* for detailed package size information.

Table 6. APEX 20K QFP, BGA & PGA Package Sizes										
Feature	144-Pin TQFP	208-Pin QFP	240-Pin QFP	356-Pin BGA	652-Pin BGA	655-Pin PGA				
Pitch (mm)	0.50	0.50	0.50	1.27	1.27	_				
Area (mm <sup>2</sup> )	484	924	1,218	1,225	2,025	3,906				
$\begin{array}{c} \text{Length} \times \text{Width} \\ \text{(mm} \times \text{mm)} \end{array}$	22 × 22	30.4 × 30.4	34.9 × 34.9	35 × 35	45 × 45	62.5 × 62.5				

Table 7. APEX 20K FineLine BGA Package Sizes									
Feature	144 Pin	324 Pin	484 Pin	672 Pin	1,020 Pin				
Pitch (mm)	1.00	1.00	1.00	1.00	1.00				
Area (mm <sup>2</sup> )	169	361	529	729	1,089				
$Length \times Width (mm \times mm)$	13 × 13	19×19	23 × 23	27 × 27	33 × 33				

All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

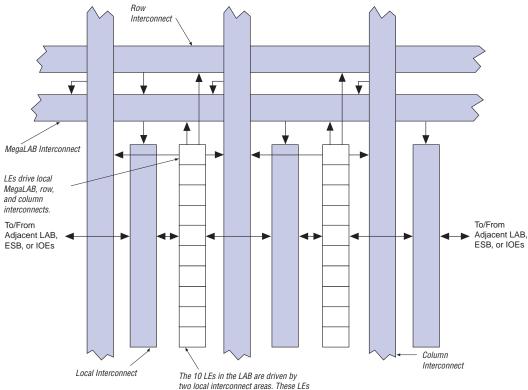
The Quartus II software provides NativeLink interfaces to other industry-standard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

# **Logic Array Block**

Each LAB consists of 10 LEs, the LEs' associated carry and cascade chains, LAB control signals, and the local interconnect. The local interconnect transfers signals between LEs in the same or adjacent LABs, IOEs, or ESBs. The Quartus II Compiler places associated logic within an LAB or adjacent LABs, allowing the use of a fast local interconnect for high performance. Figure 3 shows the APEX 20K LAB.

APEX 20K devices use an interleaved LAB structure. This structure allows each LE to drive two local interconnect areas. This feature minimizes use of the MegaLAB and FastTrack interconnect, providing higher performance and flexibility. Each LE can drive 29 other LEs through the fast local interconnect.





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can drive two local interconnect areas.

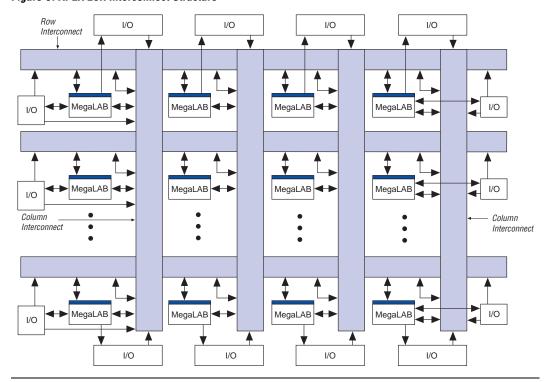


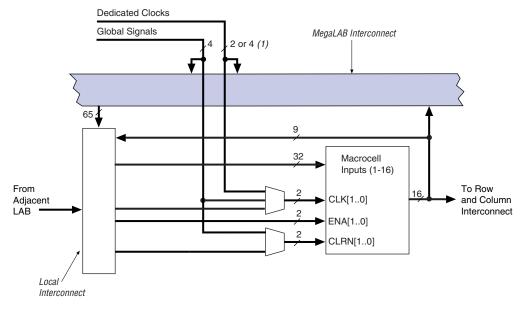
Figure 9. APEX 20K Interconnect Structure

A row line can be driven directly by LEs, IOEs, or ESBs in that row. Further, a column line can drive a row line, allowing an LE, IOE, or ESB to drive elements in a different row via the column and row interconnect. The row interconnect drives the MegaLAB interconnect to drive LEs, IOEs, or ESBs in a particular MegaLAB structure.

A column line can be directly driven by LEs, IOEs, or ESBs in that column. A column line on a device's left or right edge can also be driven by row IOEs. The column line is used to route signals from one row to another. A column line can drive a row line; it can also drive the MegaLAB interconnect directly, allowing faster connections between rows.

Figure 10 shows how the FastTrack Interconnect uses the local interconnect to drive LEs within MegaLAB structures.

Figure 13. Product-Term Logic in ESB



Note to Figure 13:

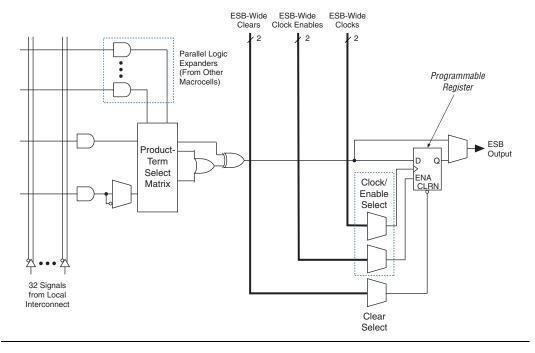
(1) APEX 20KE devices have four dedicated clocks.

#### Macrocells

APEX 20K macrocells can be configured individually for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register.

Combinatorial logic is implemented in the product terms. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as parallel expanders to be used to increase the logic available to another macrocell. One product term can be inverted; the Quartus II software uses this feature to perform DeMorgan's inversion for more efficient implementation of wide OR functions. The Quartus II software Compiler can use a NOT-gate push-back technique to emulate an asynchronous preset. Figure 14 shows the APEX 20K macrocell.

Figure 14. APEX 20K Macrocell



For registered functions, each macrocell register can be programmed individually to implement D, T, JK, or SR operation with programmable clock control. The register can be bypassed for combinatorial operation. During design entry, the designer specifies the desired register type; the Quartus II software then selects the most efficient register operation for each registered function to optimize resource utilization. The Quartus II software or other synthesis tools can also select the most efficient register operation automatically when synthesizing HDL designs.

Each programmable register can be clocked by one of two ESB-wide clocks. The ESB-wide clocks can be generated from device dedicated clock pins, global signals, or local interconnect. Each clock also has an associated clock enable, generated from the local interconnect. The clock and clock enable signals are related for a particular ESB; any macrocell using a clock also uses the associated clock enable.

If both the rising and falling edges of a clock are used in an ESB, both ESB-wide clock signals are used.



For more information on APEX 20KE devices and CAM, see *Application Note 119 (Implementing High-Speed Search Applications with APEX CAM).* 

### **Driving Signals to the ESB**

ESBs provide flexible options for driving control signals. Different clocks can be used for the ESB inputs and outputs. Registers can be inserted independently on the data input, data output, read address, write address, WE, and RE signals. The global signals and the local interconnect can drive the WE and RE signals. The global signals, dedicated clock pins, and local interconnect can drive the ESB clock signals. Because the LEs drive the local interconnect, the LEs can control the WE and RE signals and the ESB clock, clock enable, and asynchronous clear signals. Figure 24 shows the ESB control signal generation logic.

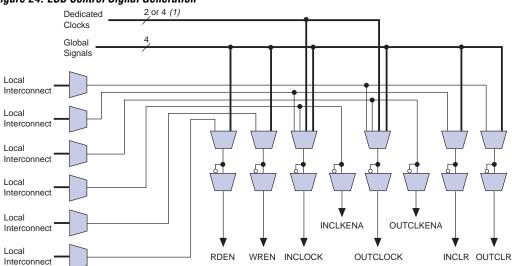


Figure 24. ESB Control Signal Generation

Note to Figure 24:

(1) APEX 20KE devices have four dedicated clocks.

An ESB is fed by the local interconnect, which is driven by adjacent LEs (for high-speed connection to the ESB) or the MegaLAB interconnect. The ESB can drive the local, MegaLAB, or FastTrack Interconnect routing structure to drive LEs and IOEs in the same MegaLAB structure or anywhere in the device.

### Implementing Logic in ROM

In addition to implementing logic with product terms, the ESB can implement logic functions when it is programmed with a read-only pattern during configuration, creating a large LUT. With LUTs, combinatorial functions are implemented by looking up the results, rather than by computing them. This implementation of combinatorial functions can be faster than using algorithms implemented in general logic, a performance advantage that is further enhanced by the fast access times of ESBs. The large capacity of ESBs enables designers to implement complex functions in one logic level without the routing delays associated with linked LEs or distributed RAM blocks. Parameterized functions such as LPM functions can take advantage of the ESB automatically. Further, the Quartus II software can implement portions of a design with ESBs where appropriate.

### **Programmable Speed/Power Control**

APEX 20K ESBs offer a high-speed mode that supports very fast operation on an ESB-by-ESB basis. When high speed is not required, this feature can be turned off to reduce the ESB's power dissipation by up to 50%. ESBs that run at low power incur a nominal timing delay adder. This Turbo Bit<sup>TM</sup> option is available for ESBs that implement product-term logic or memory functions. An ESB that is not used will be powered down so that it does not consume DC current.

Designers can program each ESB in the APEX 20K device for either high-speed or low-power operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths operate at reduced power.

# I/O Structure

The APEX 20K IOE contains a bidirectional I/O buffer and a register that can be used either as an input register for external data requiring fast setup times, or as an output register for data requiring fast clock-to-output performance. IOEs can be used as input, output, or bidirectional pins. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The Quartus II software Compiler uses the programmable inversion option to invert signals from the row and column interconnect automatically where appropriate. Because the APEX 20K IOE offers one output enable per pin, the Quartus II software Compiler can emulate open-drain operation efficiently.

The APEX 20K IOE includes programmable delays that can be activated to ensure zero hold times, minimum clock-to-output times, input IOE register-to-core register transfers, or core-to-output IOE register transfers. A path in which a pin directly drives a register may require the delay to ensure zero hold time, whereas a path in which a pin drives a register through combinatorial logic may not require the delay.

APEX 20KE devices include an enhanced IOE, which drives the FastRow interconnect. The FastRow interconnect connects a column I/O pin directly to the LAB local interconnect within two MegaLAB structures. This feature provides fast setup times for pins that drive high fan-outs with complex logic, such as PCI designs. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The APEX 20KE IOE also includes direct support for open-drain operation, giving faster clock-to-output for open-drain signals. Some programmable delays in the APEX 20KE IOE offer multiple levels of delay to fine-tune setup and hold time requirements. The Quartus II software compiler can set these delays automatically to minimize setup time while providing a zero hold time.

Table 11 describes the APEX 20KE programmable delays and their logic options in the Quartus II software.

Table 11. APEX 20KE Programmable Delay Chains						
Programmable Delays	Quartus II Logic Option					
Input Pin to Core Delay	Decrease input delay to internal cells					
Input Pin to Input Register Delay	Decrease input delay to input registers					
Core to Output Register Delay	Decrease input delay to output register					
Output Register t <sub>CO</sub> Delay	Increase delay to output pin					
Clock Enable Delay	Increase clock enable delay					

The register in the APEX 20KE IOE can be programmed to power-up high or low after configuration is complete. If it is programmed to power-up low, an asynchronous clear can control the register. If it is programmed to power-up high, an asynchronous preset can control the register. Figure 26 shows how fast bidirectional I/O pins are implemented in APEX 20KE devices. This feature is useful for cases where the APEX 20KE device controls an active-low input or another device; it prevents inadvertent activation of the input upon power-up.

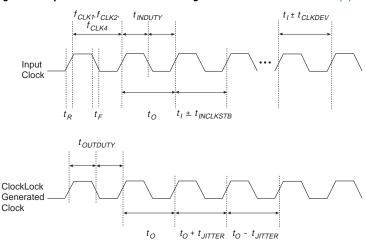


Figure 30. Specifications for the Incoming & Generated Clocks Note (1)

*Note to Figure 30:* 

(1) The tl parameter refers to the nominal input clock period; the tO parameter refers to the nominal output clock period.

Table 15 summarizes the APEX 20K ClockLock and ClockBoost parameters for -1 speed-grade devices.

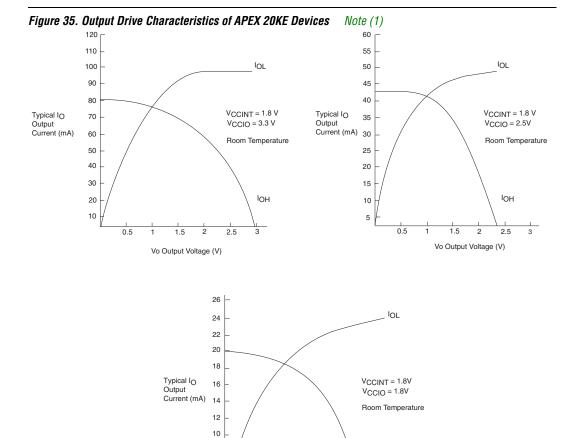
Symbol	Symbol Parameter		Max	Unit	
f <sub>OUT</sub>	Output frequency	25	180	MHz	
f <sub>CLK1</sub> (1)	Input clock frequency (ClockBoost clock multiplication factor equals 1)	25	180 (1)	MHz	
f <sub>CLK2</sub>	Input clock frequency (ClockBoost clock multiplication factor equals 2)	16	90	MHz	
f <sub>CLK4</sub>	Input clock frequency (ClockBoost clock multiplication factor equals 4)	10	48	MHz	
<sup>t</sup> OUTDUTY	Duty cycle for ClockLock/ClockBoost-generated clock	40	60	%	
f <sub>CLKDEV</sub>	Input deviation from user specification in the Quartus II software (ClockBoost clock multiplication factor equals 1) (2)		25,000 (3)	PPM	
t <sub>R</sub>	Input rise time		5	ns	
t <sub>F</sub>	Input fall time		5	ns	
t <sub>LOCK</sub>	Time required for ClockLock/ClockBoost to acquire lock (4)		10	μs	

#### Notes to Table 16:

- (1) To implement the ClockLock and ClockBoost circuitry with the Quartus II software, designers must specify the input frequency. The Quartus II software tunes the PLL in the ClockLock and ClockBoost circuitry to this frequency. The f<sub>CLKDEV</sub> parameter specifies how much the incoming clock can differ from the specified frequency during device operation. Simulation does not reflect this parameter.
- (2) Twenty-five thousand parts per million (PPM) equates to 2.5% of input clock period.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured before the rest of the device. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration because the  $t_{LOCK}$  value is less than the time required for configuration.
- (4) The  $t_{IITTER}$  specification is measured under long-term observation.

Tables 17 and 18 summarize the ClockLock and ClockBoost parameters for APEX 20KE devices.

Table 17. APEX 20KE ClockLock & ClockBoost Parameters Note (1)								
Symbol	Parameter	Conditions	Min	Тур	Max	Unit		
t <sub>R</sub>	Input rise time				5	ns		
t <sub>F</sub>	Input fall time				5	ns		
t <sub>INDUTY</sub>	Input duty cycle		40		60	%		
t <sub>INJITTER</sub>	Input jitter peak-to-peak				2% of input period	peak-to- peak		
t <sub>OUTJITTER</sub>	Jitter on ClockLock or ClockBoost- generated clock				0.35% of output period	RMS		
t <sub>OUTDUTY</sub>	Duty cycle for ClockLock or ClockBoost-generated clock		45		55	%		
t <sub>LOCK</sub> (2), (3)	Time required for ClockLock or ClockBoost to acquire lock				40	μs		



8

4 2

0.5

Figure 35 shows the output drive characteristics of APEX 20KE devices.

Note to Figure 35:

(1) These are transient (AC) currents.

# **Timing Model**

The high-performance FastTrack and MegaLAB interconnect routing resources ensure predictable performance, accurate simulation, and accurate timing analysis. This predictable performance contrasts with that of FPGAs, which use a segmented connection scheme and therefore have unpredictable performance.

Vo Output Voltage (V)

IOH

2.0

Symbol	Parameter	Conditions
t <sub>INSUBIDIR</sub>	Setup time for bidirectional pins with global clock at LAB adjacent Input Register	
t <sub>INHBIDIR</sub>	Hold time for bidirectional pins with global clock at LAB adjacent Input Register	
<sup>t</sup> OUTCOBIDIR	Clock-to-output delay for bidirectional pins with global clock at IOE output register	C1 = 10 pF
t <sub>XZBIDIR</sub>	Synchronous Output Enable Register to output buffer disable delay	C1 = 10 pF
t <sub>ZXBIDIR</sub>	Synchronous Output Enable Register output buffer enable delay	C1 = 10 pF
t <sub>INSUBIDIRPLL</sub>	Setup time for bidirectional pins with PLL clock at LAB adjacent Input Register	
t <sub>INHBIDIRPLL</sub>	Hold time for bidirectional pins with PLL clock at LAB adjacent Input Register	
<sup>†</sup> OUTCOBIDIRPLL	Clock-to-output delay for bidirectional pins with PLL clock at IOE output register	C1 = 10 pF
t <sub>XZBIDIRPLL</sub>	Synchronous Output Enable Register to output buffer disable delay with PLL	C1 = 10 pF
t <sub>ZXBIDIRPLL</sub>	Synchronous Output Enable Register output buffer enable delay with PLL	C1 = 10 pF

Note to Tables 38 and 39:

<sup>(1)</sup> These timing parameters are sample-tested only.

Table 43. EP20K100 External Timing Parameters									
Symbol	-1 Spe	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade			
	Min	Max	Min	Max	Min	Max			
t <sub>INSU</sub> (1)	2.3		2.8		3.2		ns		
t <sub>INH</sub> (1)	0.0		0.0		0.0		ns		
t <sub>OUTCO</sub> (1)	2.0	4.5	2.0	4.9	2.0	6.6	ns		
t <sub>INSU</sub> (2)	1.1		1.2		-		ns		
t <sub>INH</sub> (2)	0.0		0.0		-		ns		
t <sub>OUTCO</sub> (2)	0.5	2.7	0.5	3.1	_	4.8	ns		

Symbol	-1 Speed Grade		-2 Spee	-2 Speed Grade		d Grade	Unit
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub> (1)	2.3		2.8		3.2		ns
t <sub>INHBIDIR</sub> (1)	0.0		0.0		0.0		ns
toutcobidir (1)	2.0	4.5	2.0	4.9	2.0	6.6	ns
t <sub>XZBIDIR</sub> (1)		5.0		5.9		6.9	ns
t <sub>ZXBIDIR</sub> (1)		5.0		5.9		6.9	ns
t <sub>INSUBIDIR</sub> (2)	1.0		1.2		-		ns
t <sub>INHBIDIR</sub> (2)	0.0		0.0		-		ns
toutcobidir (2)	0.5	2.7	0.5	3.1	-	-	ns
t <sub>XZBIDIR</sub> (2)		4.3		5.0		_	ns
t <sub>ZXBIDIR</sub> (2)		4.3		5.0		_	ns

Table 45. EP20K200 External Timing Parameters									
Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit		
	Min	Max	Min	Max	Min	Max			
t <sub>INSU</sub> (1)	1.9		2.3		2.6		ns		
t <sub>INH</sub> (1)	0.0		0.0		0.0		ns		
t <sub>OUTCO</sub> (1)	2.0	4.6	2.0	5.6	2.0	6.8	ns		
t <sub>INSU</sub> (2)	1.1		1.2		-		ns		
t <sub>INH</sub> (2)	0.0		0.0		-		ns		
t <sub>оитсо</sub> <i>(2)</i>	0.5	2.7	0.5	3.1	-	_	ns		

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t <sub>ESBARC</sub>		2.03		2.86		4.24	ns
t <sub>ESBSRC</sub>		2.58		3.49		5.02	ns
t <sub>ESBAWC</sub>		3.88		5.45		8.08	ns
t <sub>ESBSWC</sub>		4.08		5.35		7.48	ns
t <sub>ESBWASU</sub>	1.77		2.49		3.68		ns
t <sub>ESBWAH</sub>	0.00		0.00		0.00		ns
t <sub>ESBWDSU</sub>	1.95		2.74		4.05		ns
t <sub>ESBWDH</sub>	0.00		0.00		0.00		ns
t <sub>ESBRASU</sub>	1.96		2.75		4.07		ns
t <sub>ESBRAH</sub>	0.00		0.00		0.00		ns
t <sub>ESBWESU</sub>	1.80		2.73		4.28		ns
t <sub>ESBWEH</sub>	0.00		0.00		0.00		ns
t <sub>ESBDATASU</sub>	0.07		0.48		1.17		ns
t <sub>ESBDATAH</sub>	0.13		0.13		0.13		ns
t <sub>ESBWADDRSU</sub>	0.30		0.80		1.64		ns
t <sub>ESBRADDRSU</sub>	0.37		0.90		1.78		ns
t <sub>ESBDATACO1</sub>		1.11		1.32		1.67	ns
t <sub>ESBDATACO2</sub>		2.65		3.73		5.53	ns
t <sub>ESBDD</sub>		3.88		5.45		8.08	ns
t <sub>PD</sub>		1.91	_	2.69		3.98	ns
t <sub>PTERMSU</sub>	1.04		1.71		2.82		ns
t <sub>PTERMCO</sub>		1.13		1.34		1.69	ns

Table 51. EP20K30E f <sub>MAX</sub> Routing Delays								
Symbol		1	-2		-3		Unit	
	Min	Max	Min	Max	Min	Max		
t <sub>F1-4</sub>		0.24		0.27		0.31	ns	
t <sub>F5-20</sub>		1.03		1.14		1.30	ns	
t <sub>F20+</sub>		1.42		1.54		1.77	ns	

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	7
t <sub>ESBARC</sub>		1.67		1.91		1.99	ns
t <sub>ESBSRC</sub>		2.30		2.66		2.93	ns
t <sub>ESBAWC</sub>		3.09		3.58		3.99	ns
t <sub>ESBSWC</sub>		3.01		3.65		4.05	ns
t <sub>ESBWASU</sub>	0.54		0.63		0.65		ns
t <sub>ESBWAH</sub>	0.36		0.43		0.42		ns
t <sub>ESBWDSU</sub>	0.69		0.77		0.84		ns
t <sub>ESBWDH</sub>	0.36		0.43		0.42		ns
t <sub>ESBRASU</sub>	1.61		1.77		1.86		ns
t <sub>ESBRAH</sub>	0.00		0.00		0.01		ns
t <sub>ESBWESU</sub>	1.35		1.47		1.61		ns
t <sub>ESBWEH</sub>	0.00		0.00		0.00		ns
t <sub>ESBDATASU</sub>	-0.18		-0.30		-0.27		ns
t <sub>ESBDATAH</sub>	0.13		0.13		0.13		ns
t <sub>ESBWADDRSU</sub>	-0.02		-0.11		-0.03		ns
t <sub>ESBRADDRSU</sub>	0.06		-0.01		-0.05		ns
t <sub>ESBDATACO1</sub>		1.16		1.40		1.54	ns
t <sub>ESBDATACO2</sub>		2.18		2.55		2.85	ns
t <sub>ESBDD</sub>		2.73		3.17		3.58	ns
t <sub>PD</sub>		1.57		1.83		2.07	ns
t <sub>PTERMSU</sub>	0.92		0.99		1.18		ns
t <sub>PTERMCO</sub>		1.18		1.43		1.17	ns

Table 110. Selectable I/O Standard Output Delays								
Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit	
	Min	Max	Min	Max	Min	Max	Min	
LVCMOS		0.00		0.00		0.00	ns	
LVTTL		0.00		0.00		0.00	ns	
2.5 V		0.00		0.09		0.10	ns	
1.8 V		2.49		2.98		3.03	ns	
PCI		-0.03		0.17		0.16	ns	
GTL+		0.75		0.75		0.76	ns	
SSTL-3 Class I		1.39		1.51		1.50	ns	
SSTL-3 Class II		1.11		1.23		1.23	ns	
SSTL-2 Class I		1.35		1.48		1.47	ns	
SSTL-2 Class II		1.00		1.12		1.12	ns	
LVDS		-0.48		-0.48		-0.48	ns	
CTT		0.00		0.00		0.00	ns	
AGP		0.00	•	0.00		0.00	ns	

# Power Consumption

To estimate device power consumption, use the interactive power calculator on the Altera web site at http://www.altera.com.

# Configuration & Operation

The APEX 20K architecture supports several configuration schemes. This section summarizes the device operating modes and available device configuration schemes.

# **Operating Modes**

The APEX architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after configuration, the device resets registers, enables I/O pins, and begins to operate as a logic device. The I/O pins are tri-stated during power-up, and before and during configuration. Together, the configuration and initialization processes are called *command mode*; normal device operation is called *user mode*.

Before and during device configuration, all I/O pins are pulled to  $V_{\mbox{\scriptsize CCIO}}$  by a built-in weak pull-up resistor.

## Version 4.1

APEX 20K Programmable Logic Device Family Data Sheet version 4.1 contains the following changes:

- t<sub>ESBWEH</sub> added to Figure 37 and Tables 35, 50, 56, 62, 68, 74, 86, 92, 97, and 104.
- Updated EP20K300E device internal and external timing numbers in Tables 79 through 84.



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